

**Firm, Insulating and Electrically Conducting Connection of Processed Semiconductor Wafers**

The invention relates to a process for and an arrangement of the connection of processed semiconductor wafers (1, 2) wherein, in addition to the firm connection, there is an electric connection (5) between the semiconductor wafers and/or the electronic structures (3) supporting them. For this purpose, low-melting structured intermediate glass layers (6; 6a) are used as insulating layers and as an electric connection in the form of electrically conductive solder (5) on a glass basis in order to achieve a firm connection.

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